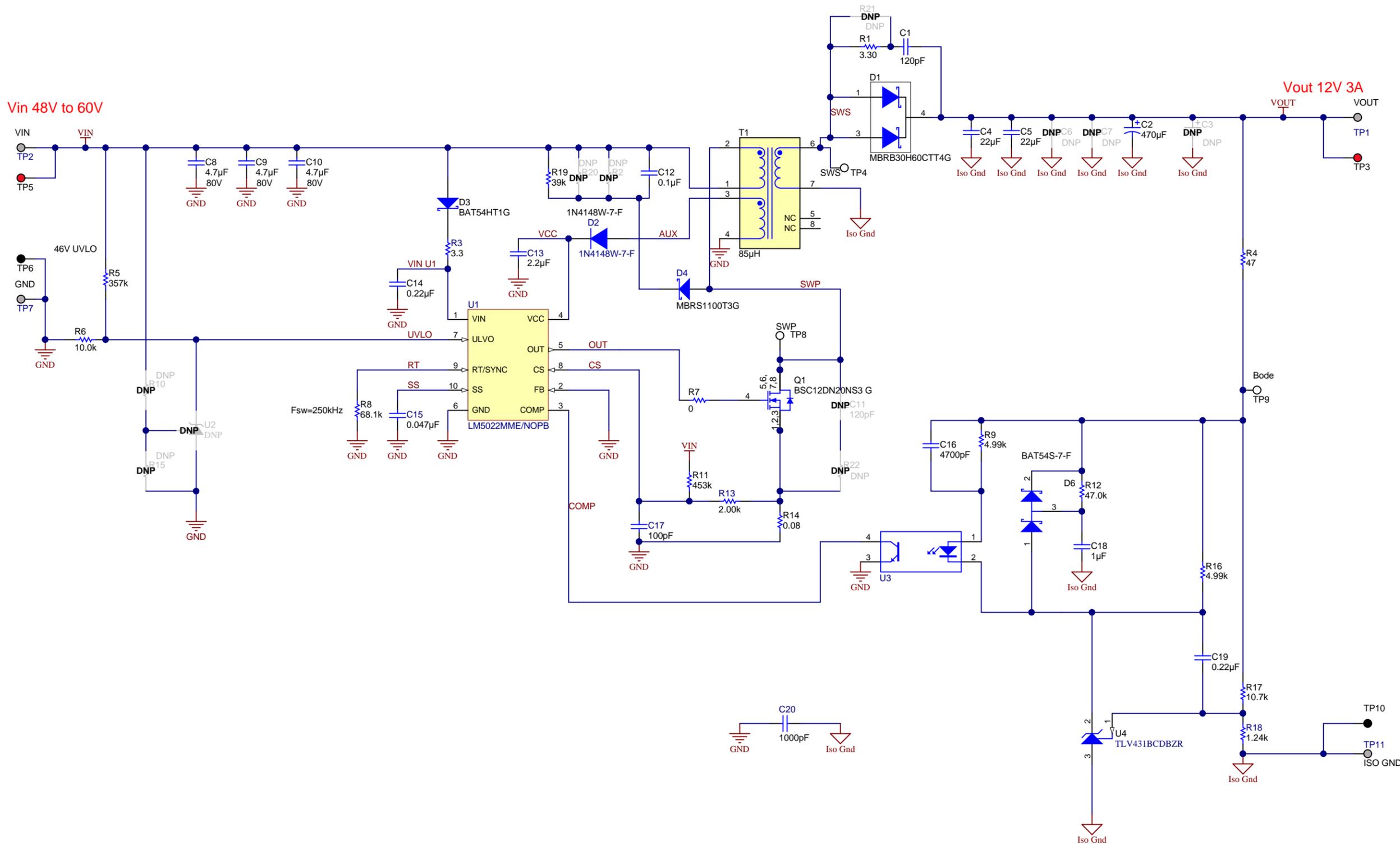


Vin 48V to 60V

Vout 12V 3A



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Orderable: <a href="#">ChangeMe!</a>	Designed for: Public Release	Mod. Date: 1/30/2017
TID #: PMP20692	Project Title: LM5022 54Vin to 12Vout @ 3A Flyback	
Number: PMP20692	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 2
Drawn By:	File: PMP20692_REVA.SchDoc	Size: B
Engineer: Xinyu Dai	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



H1 NY PMS 440 0025 PH  
 H2 NY PMS 440 0025 PH  
 H3 NY PMS 440 0025 PH  
 H4 NY PMS 440 0025 PH

H5 1902C  
 H6 1902C  
 H7 1902C  
 H8 1902C

DNP FID1  
 DNP FID2  
 DNP FID3

!PCB?  
 PCB: PMP20551 RevA  
 PMP20551 RevA

PCB  
 LOGO  
 FCC disclaimer

Variant/Label Table	
Variant	Label Text
001	

ZZ1  
 Label Assembly Note  
 This Assembly Note is for PCB labels only

ZZ2  
 Assembly Note  
 These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
 Assembly Note  
 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
 Assembly Note  
 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: <a href="#">ChangeMe!</a>	Designed for: <a href="#">Public Release</a>	Mod. Date: 1/24/2017
TID #: PMP20692	Project Title: LM5022 54Vin to 12Vout @ 3A Flyback	
Number: PMP20692	Rev: A	Sheet: 2 of 2
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 2
Drawn By:	File: PMP20692_REVA_Hardware.SchDoc	Size: B
Engineer: Xinyu Dai	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	

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